

Maximum Ratings (@T_A = 25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage	V _{RRM}	100	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	71	V
Forward Continuous Current (Note 5)	I _{FM}	200	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	@ t = 1.0μs	4.0
		@ t = 1.0ms	1.0
		@ t = 1.0s	0.5

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	350	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = 25°C unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	100	—	V	I _R = 100μA
Forward Voltage	V _F	—	0.715	V	I _F = 1.0mA
		—	0.855		I _F = 10mA
		—	1.0		I _F = 50mA
		—	1.25		I _F = 150mA
		—	0.5		V _R = 80V
Leakage Current (Note 6)	I _R	—	50	μA	V _R = 80V, T _J = 150°C
		—	30	μA	V _R = 25V, T _J = 150°C
		—	30	nA	V _R = 25V
		—	1.5	pF	V _R = 0, f = 1.0MHz
Total Capacitance	C _T	—	1.5	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	4.0	ns	I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω

Notes: 5. Device mounted on FR-4 PCB, on minimum recommended, 2oz copper pad layout.
 6. Short duration pulse test used to minimize self-heating effect.

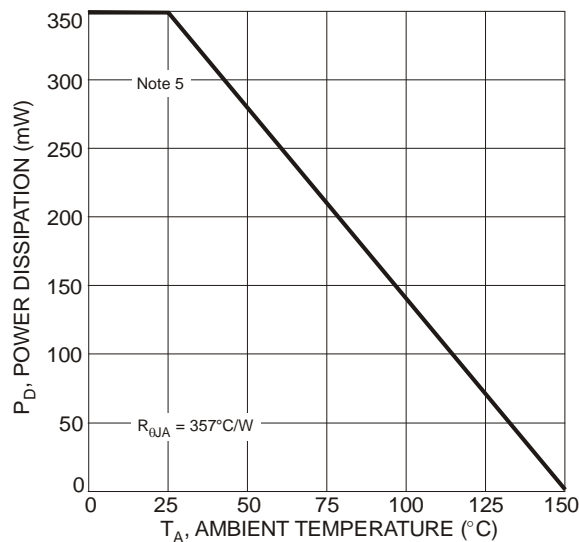


Fig. 1 Power Derating Curve, Total Package

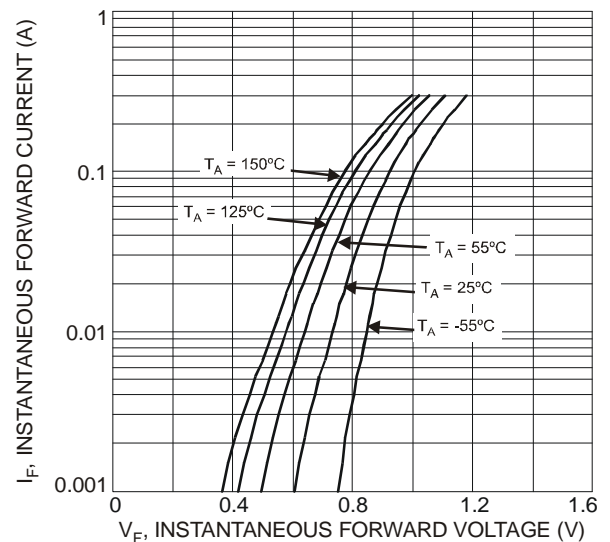


Fig. 2 Typical Forward Characteristics, Per Element

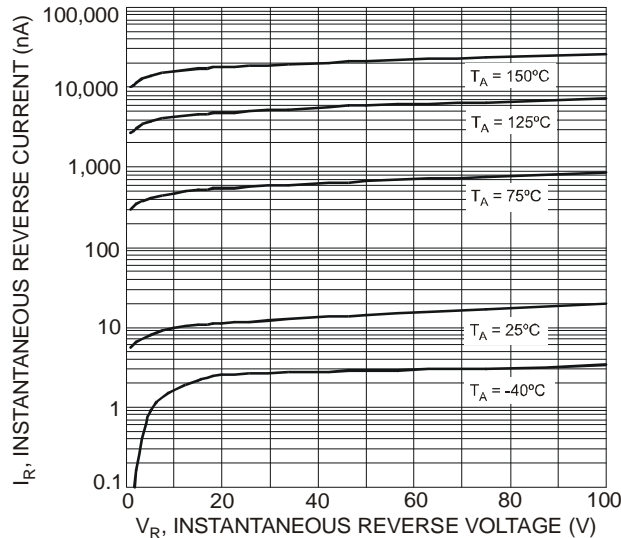


Fig. 3 Typical Reverse Characteristics, Per Element

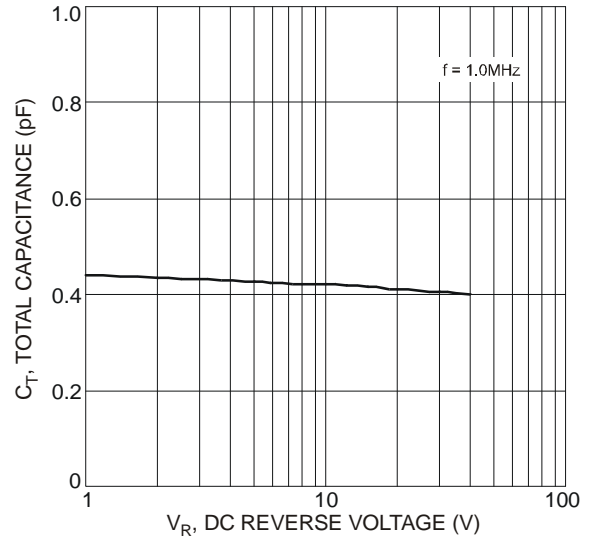
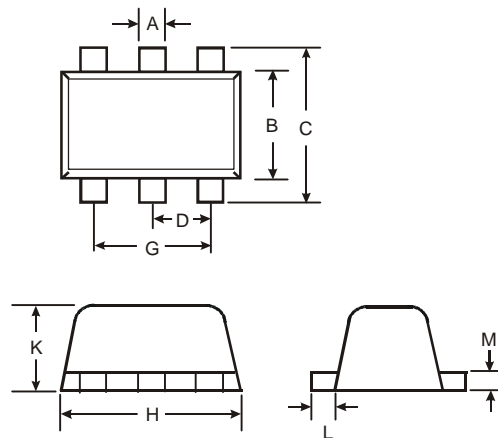


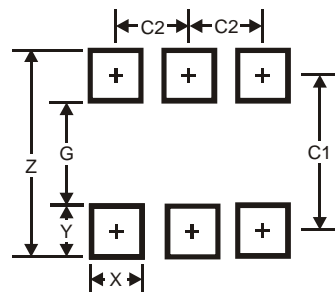
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions



SOT563			
Dim	Min	Max	Typ
A	0.15	0.30	0.20
B	1.10	1.25	1.20
C	1.55	1.70	1.60
D	-	-	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
K	0.55	0.60	0.60
L	0.10	0.30	0.20
M	0.10	0.18	0.11
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

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